

NEXT-100 Energy plane

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with much valuable input from (among others):

- D. Nygren
- A. Goldschmidt
- T. Miller
- G. Pryzbilski
- I. Liubarsky
- S. Carcel
- V. Alvarez
- A. Martinez

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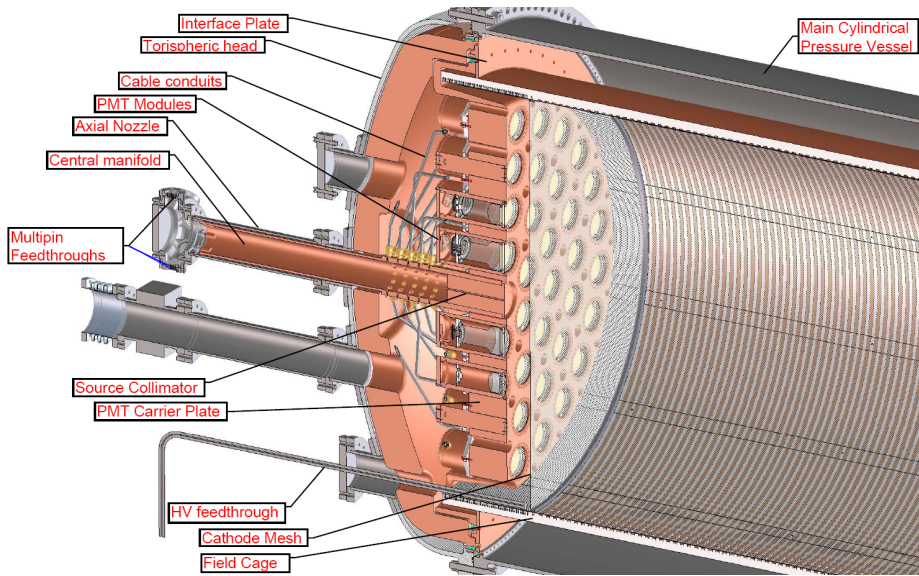
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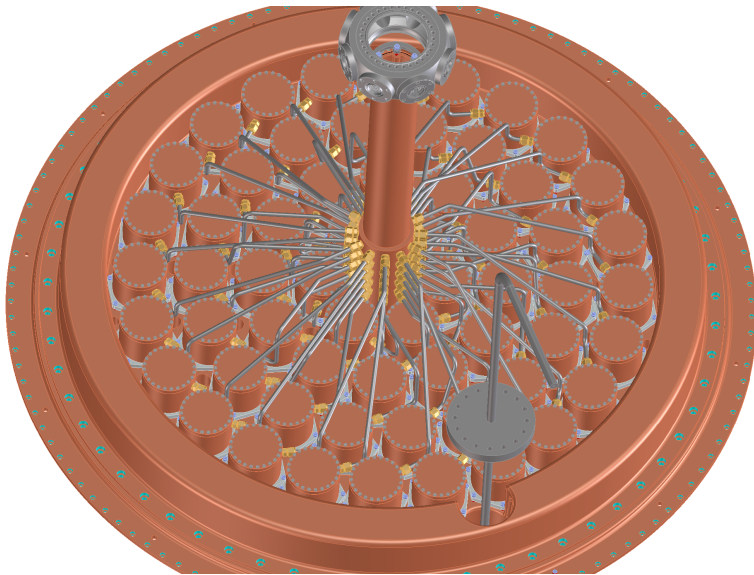
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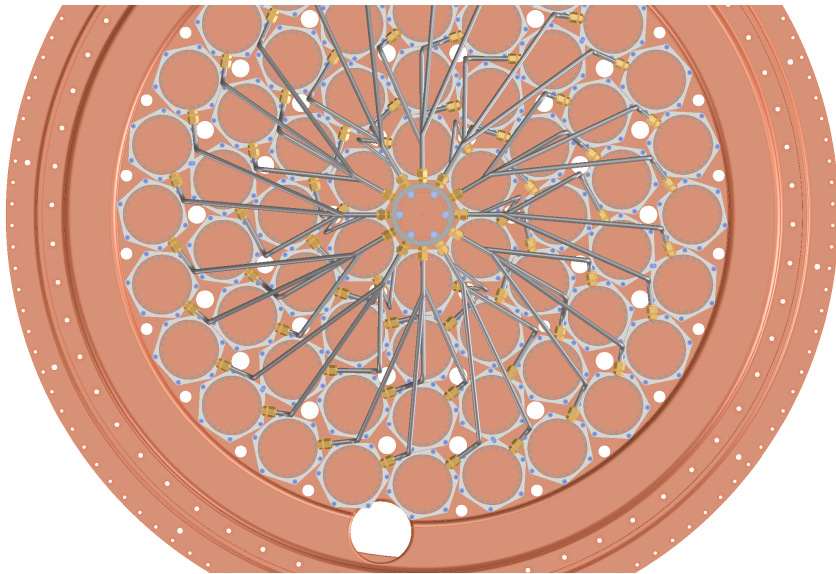
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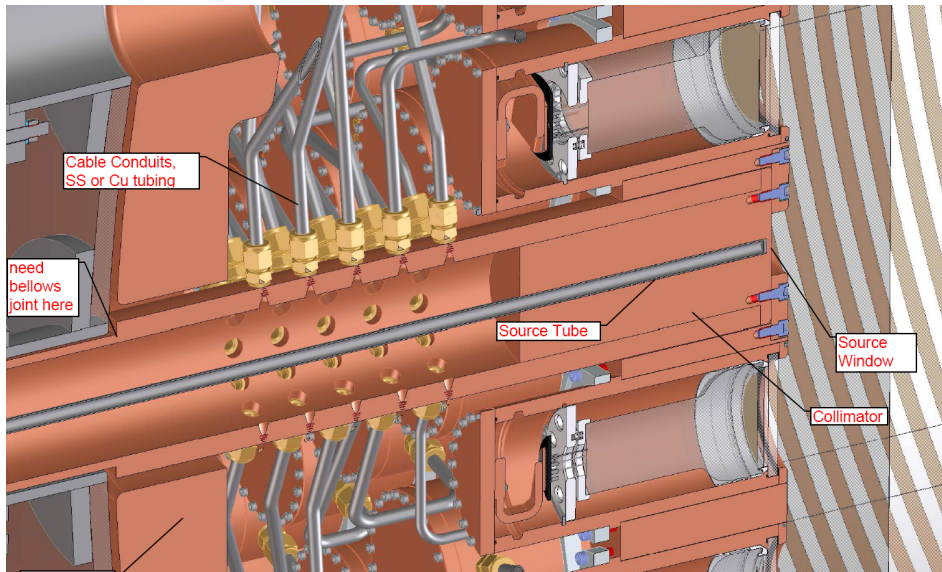
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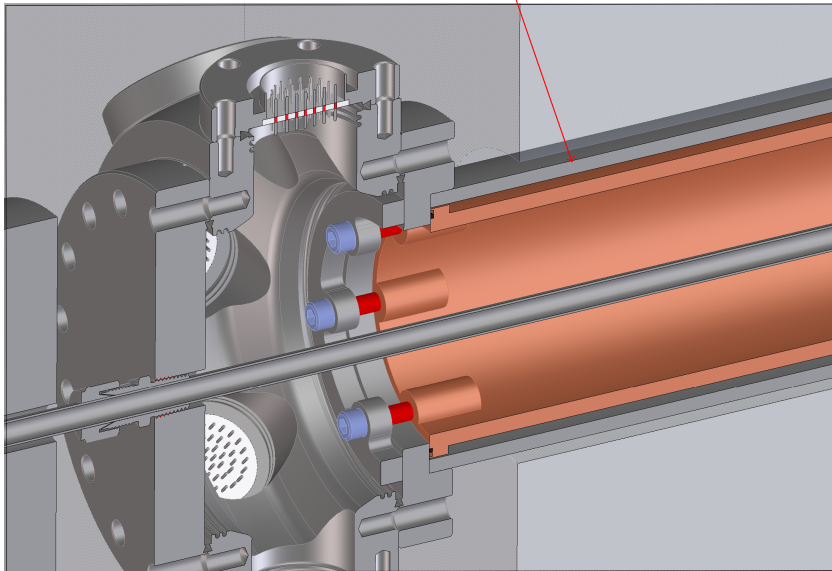






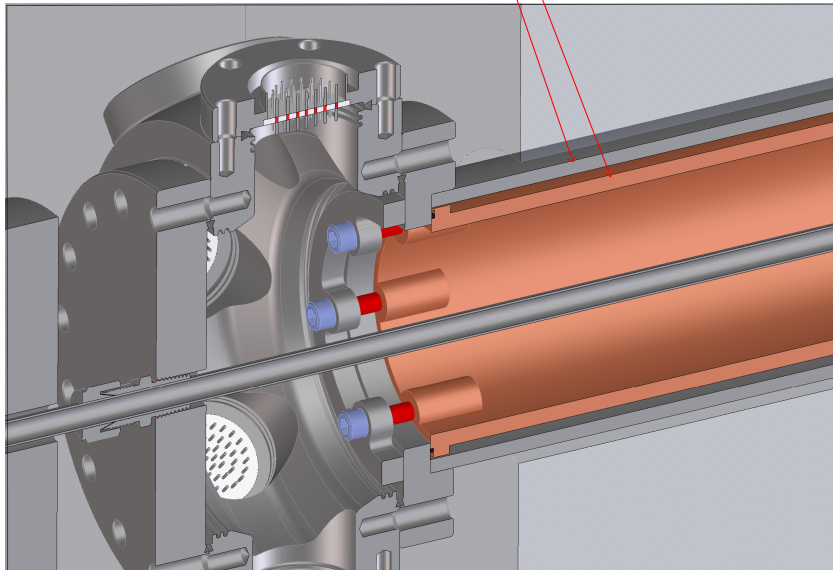


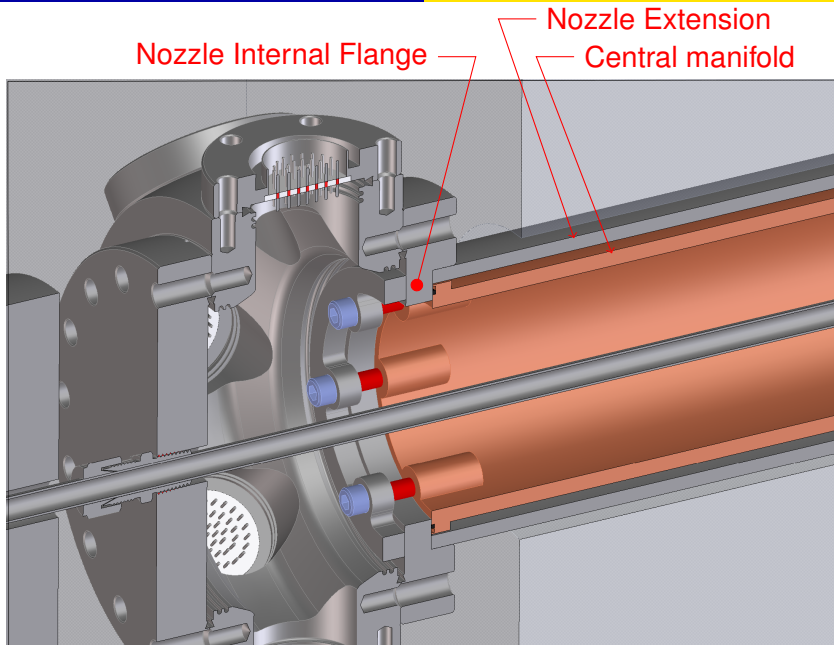
Nozzle Extension

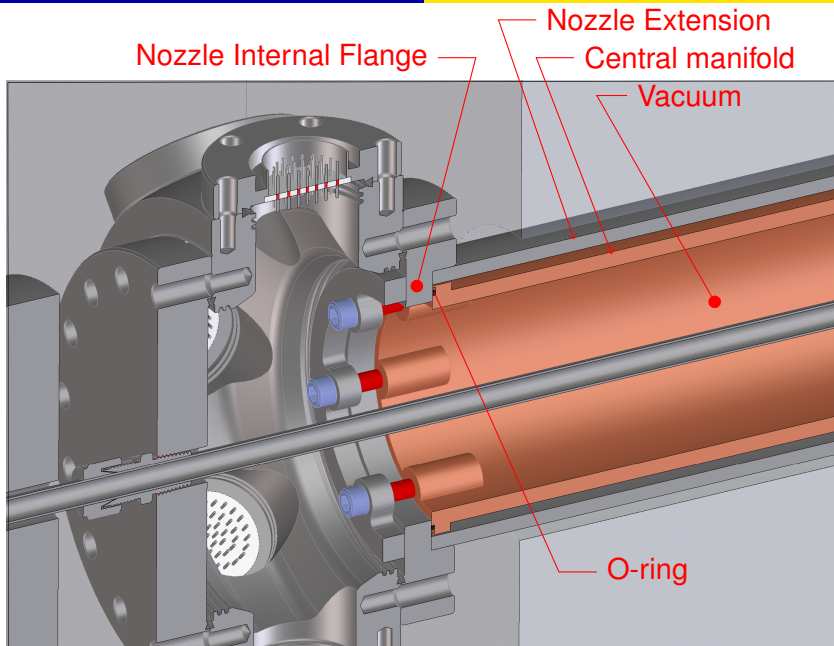


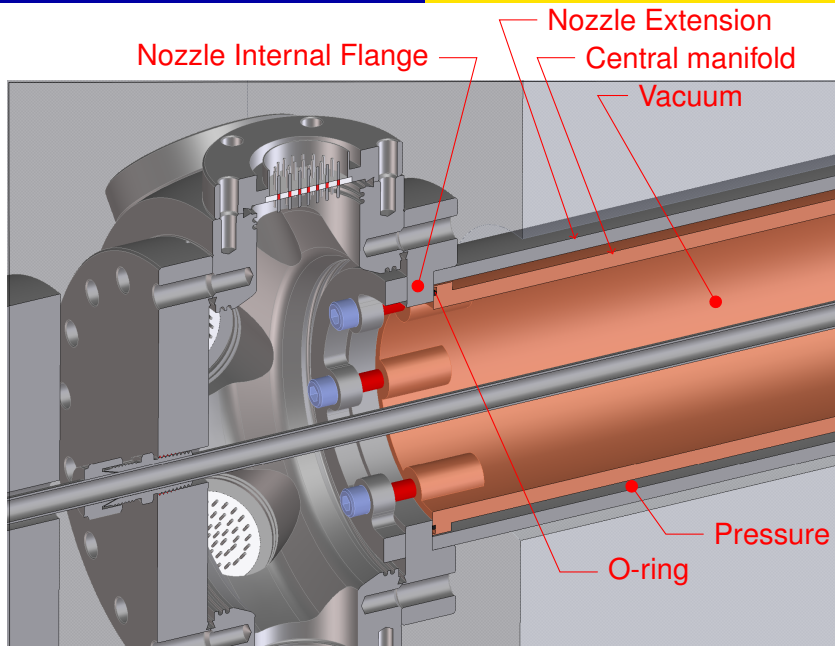
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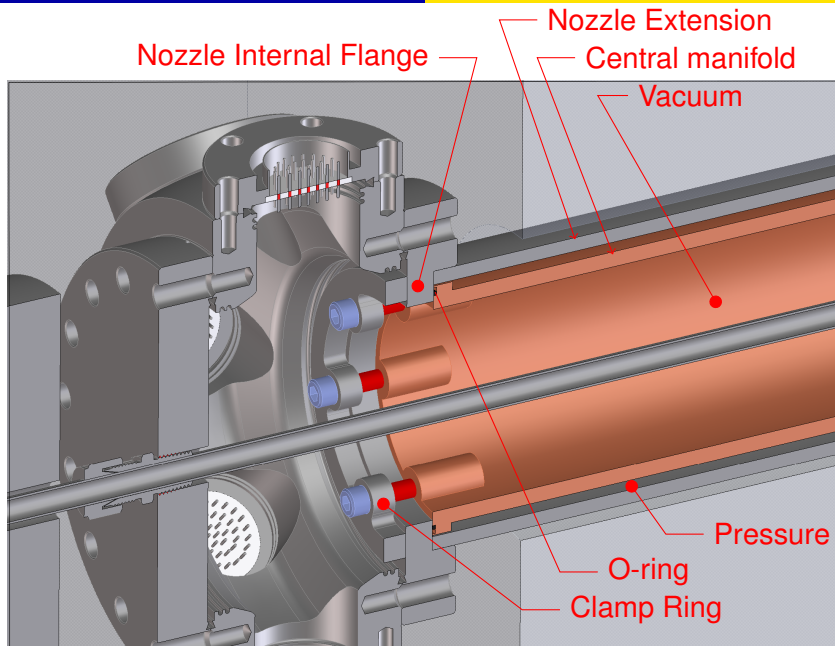
Central manifold

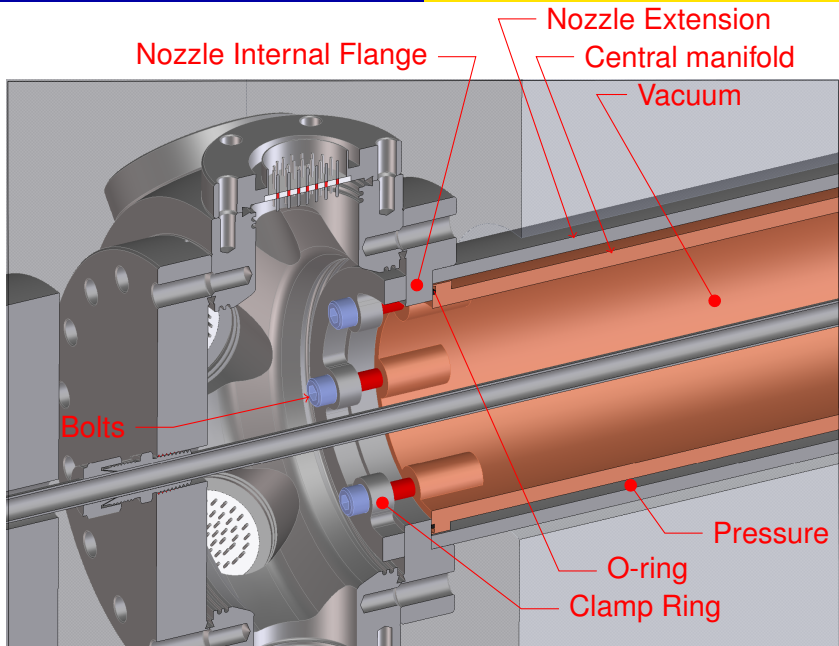


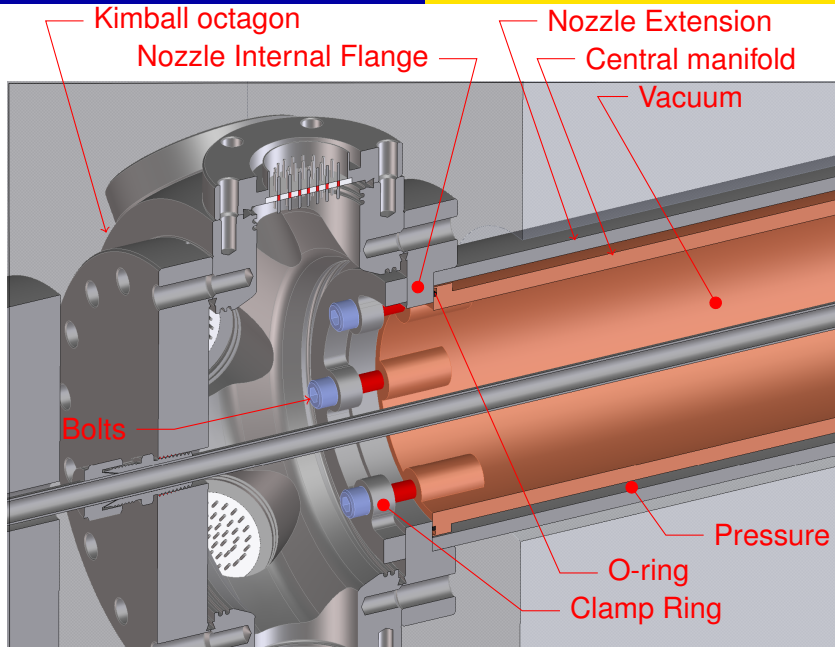


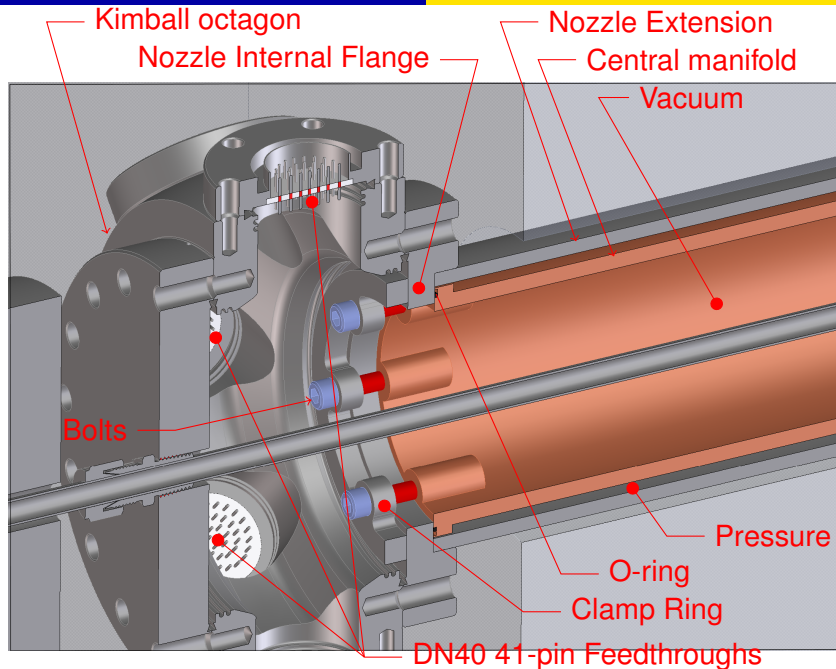


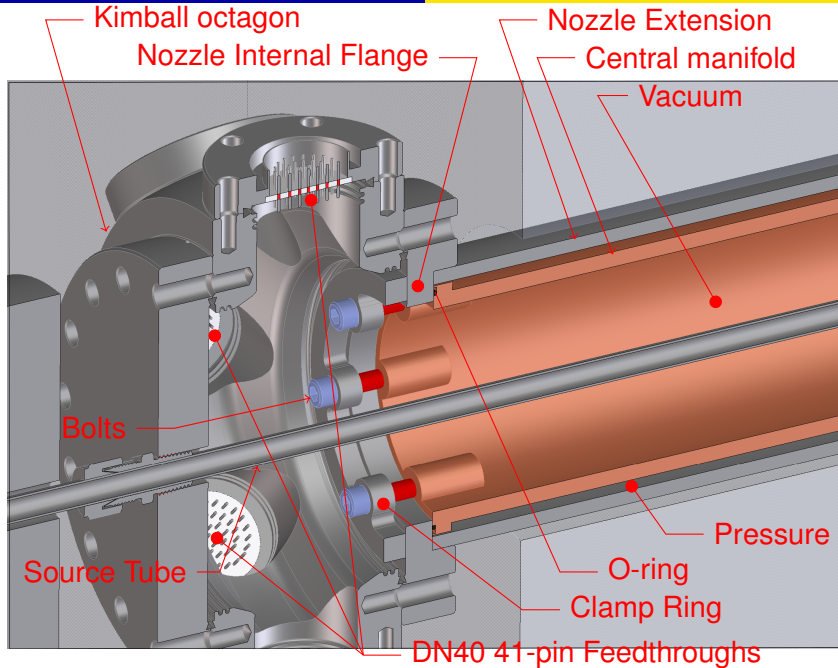


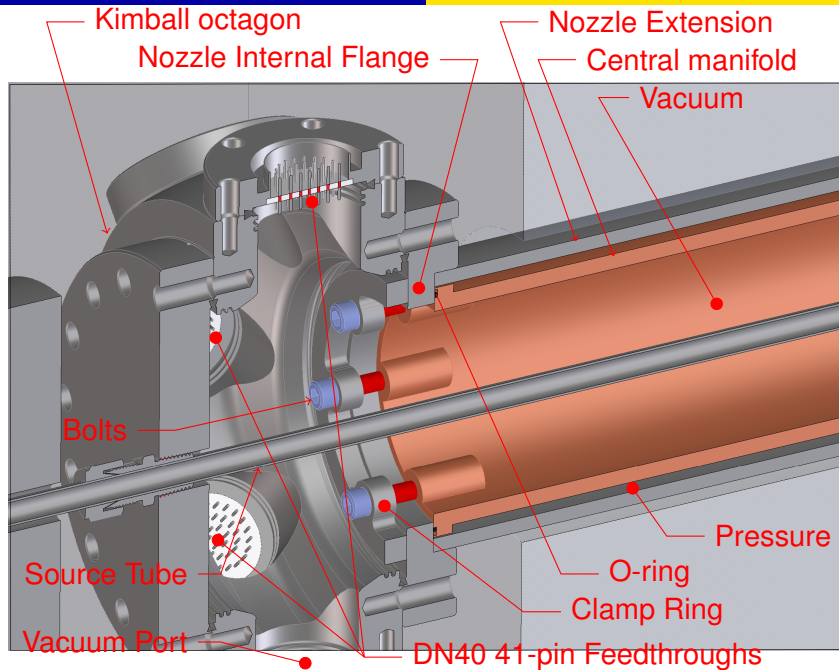


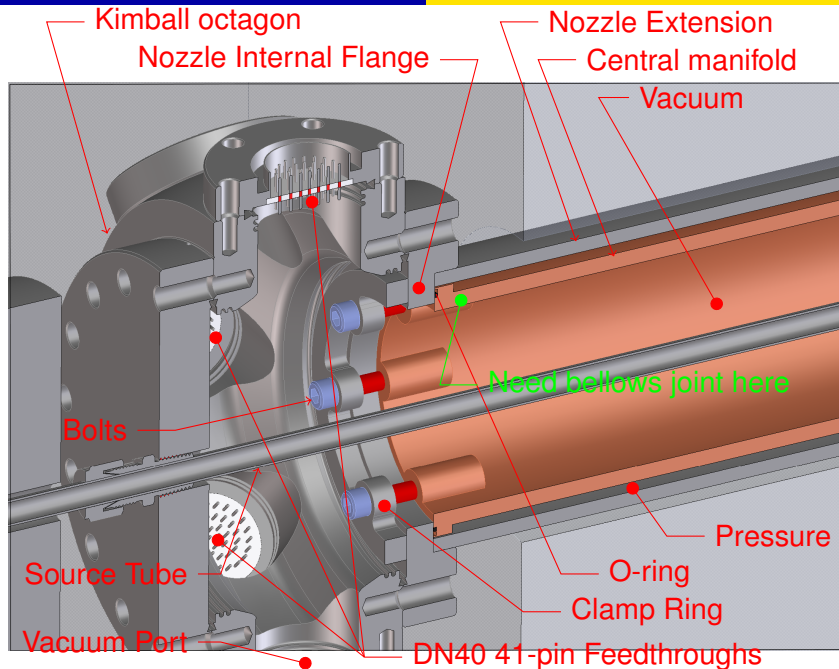












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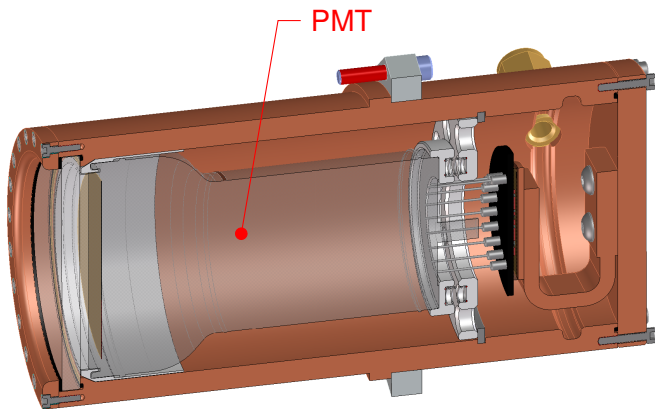
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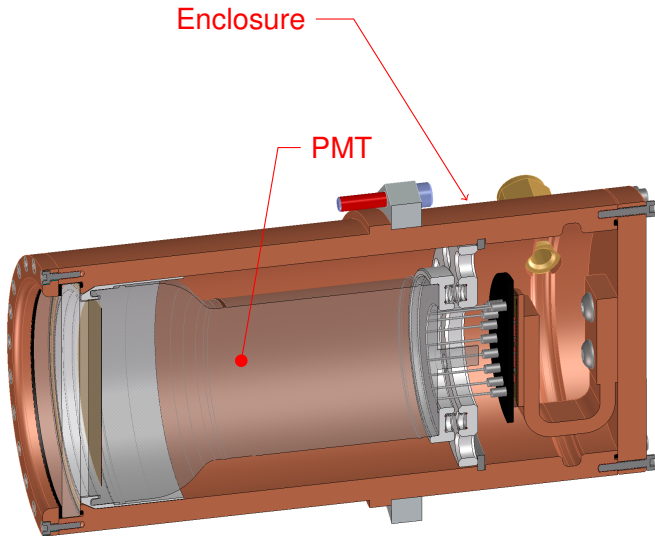
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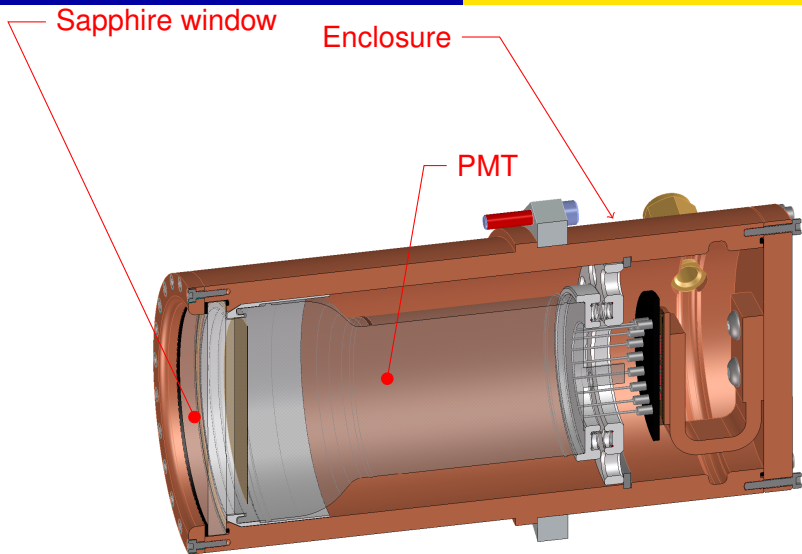
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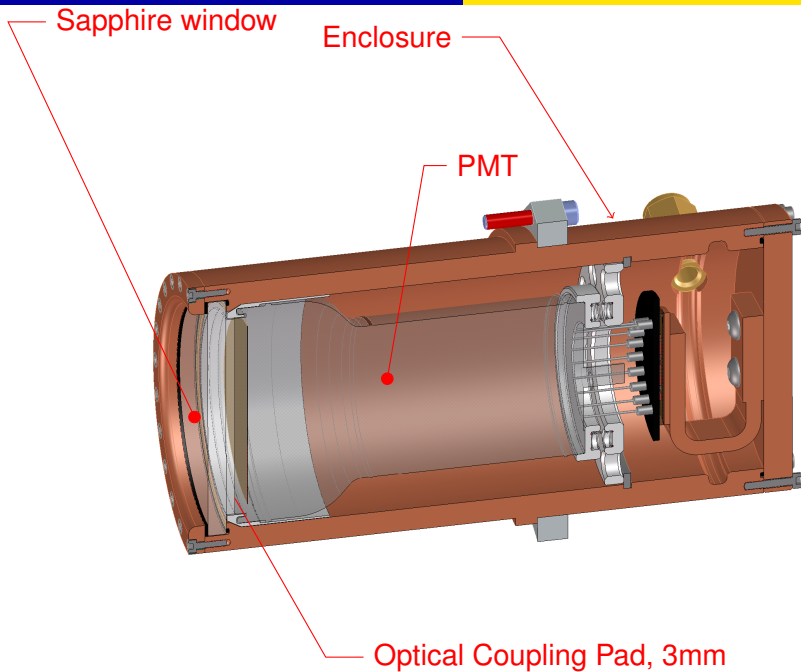
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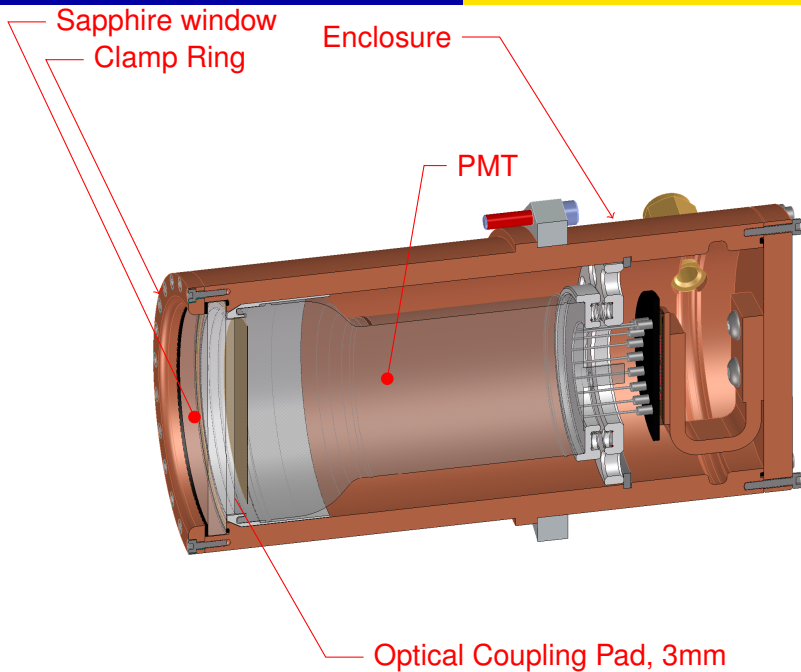
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- Carrier plate will be redesigned for adjustable buffer distance

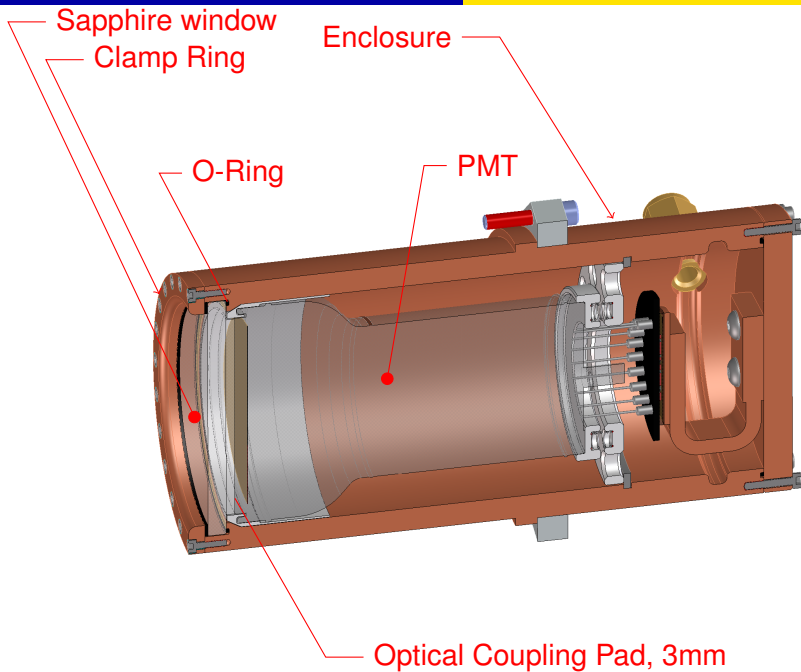


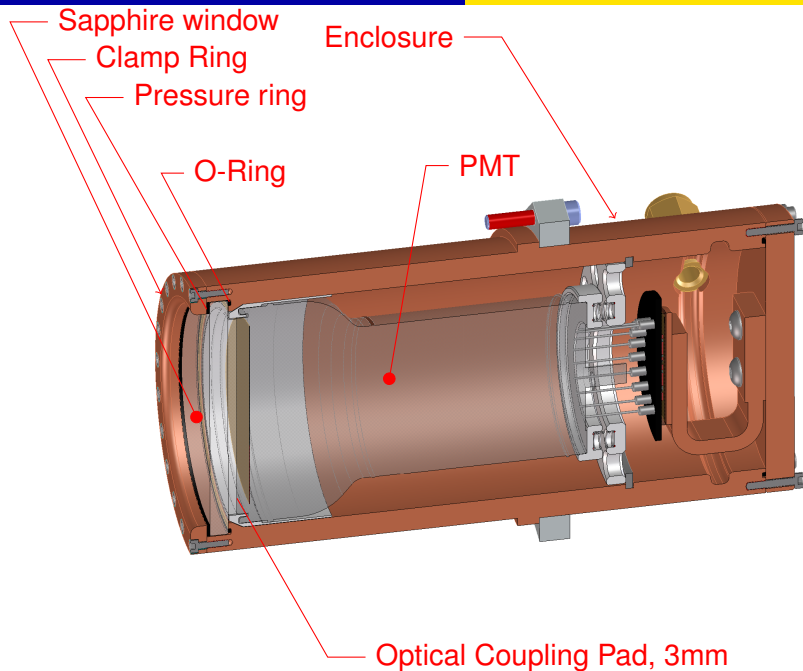


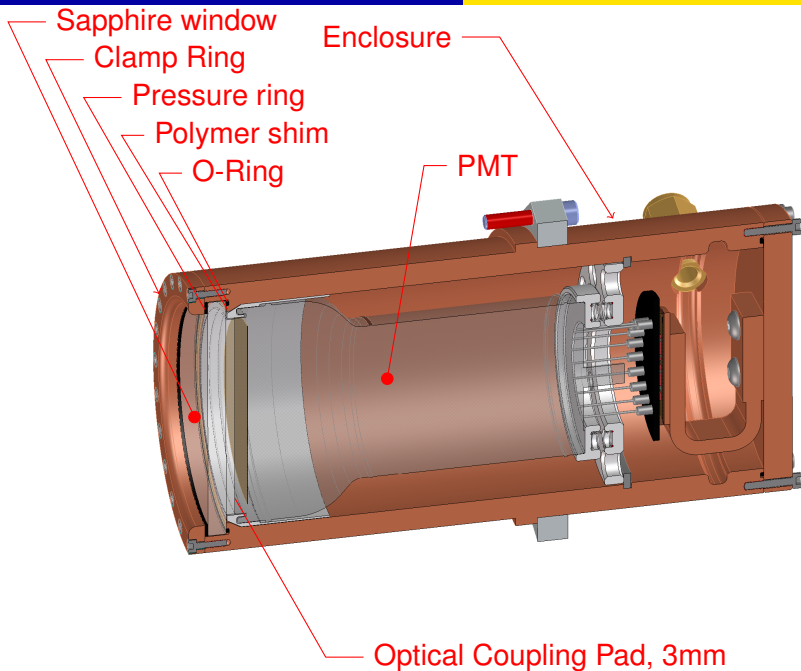


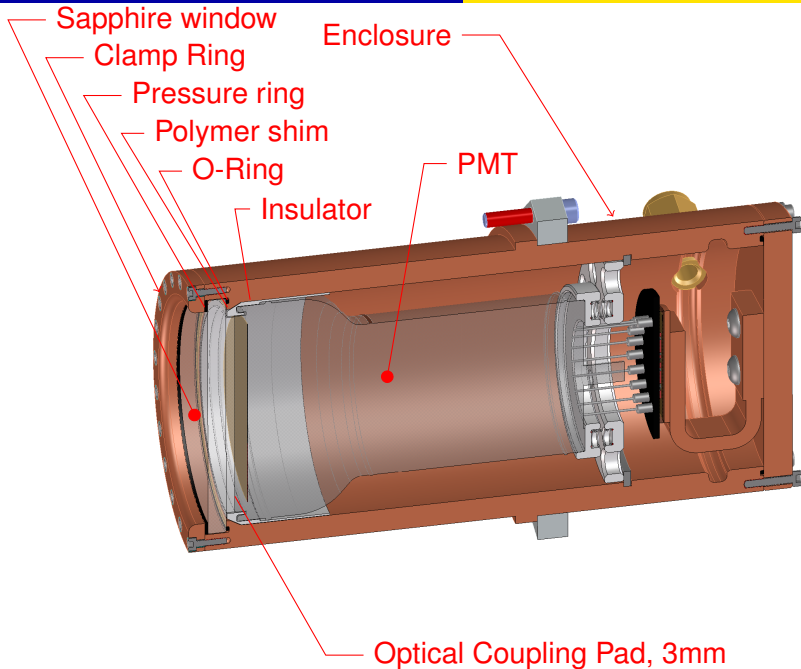


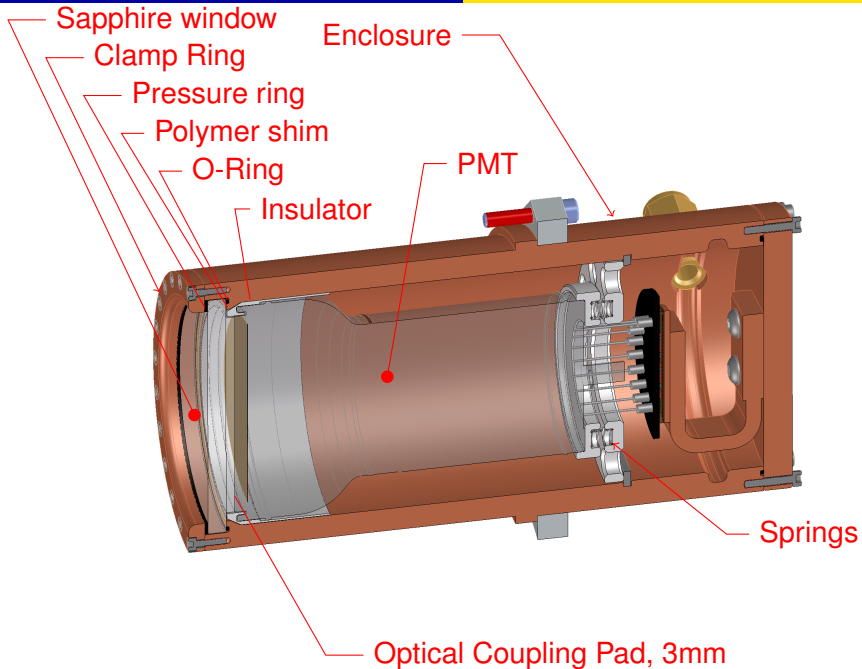


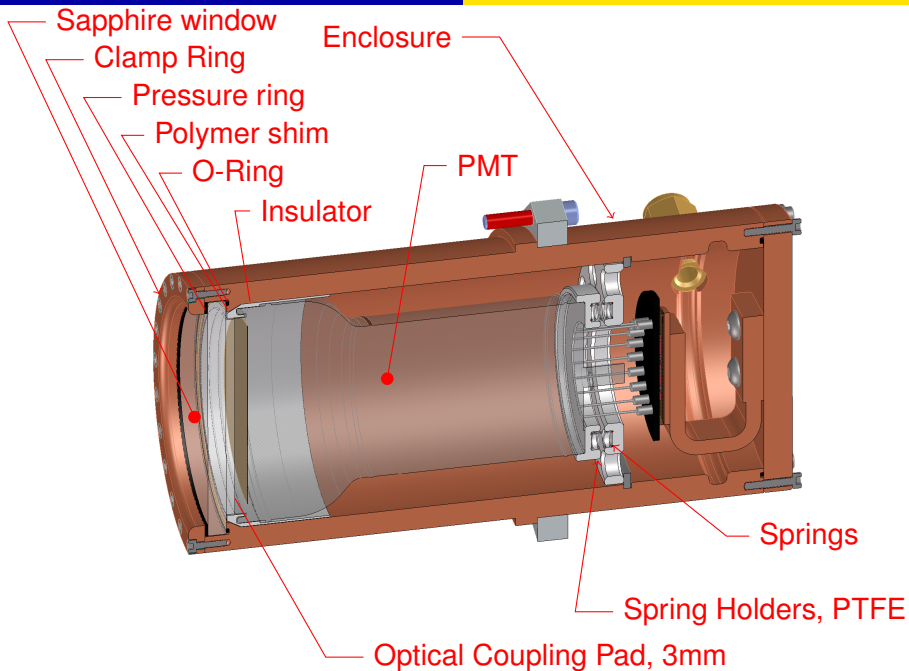


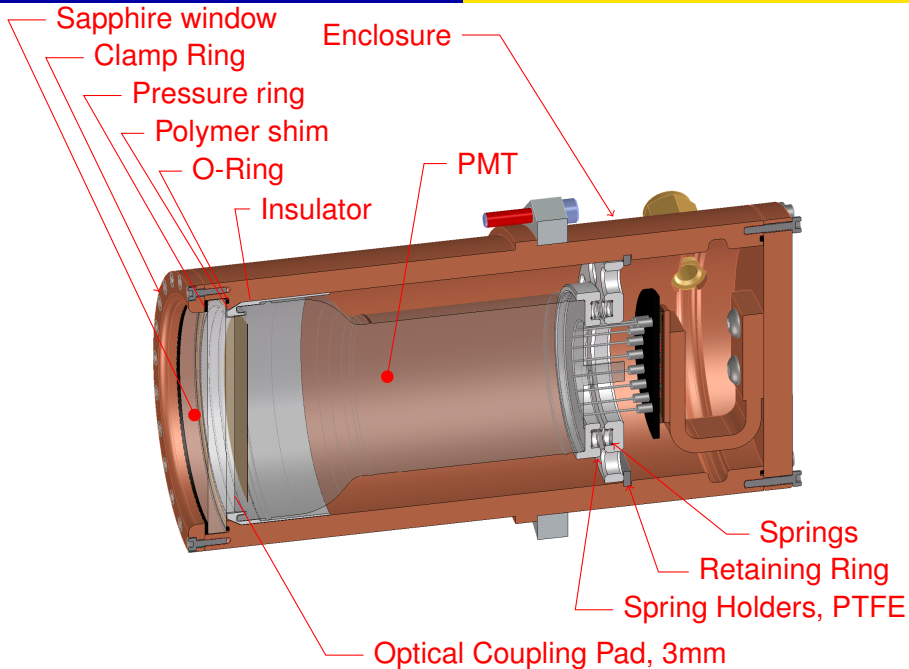


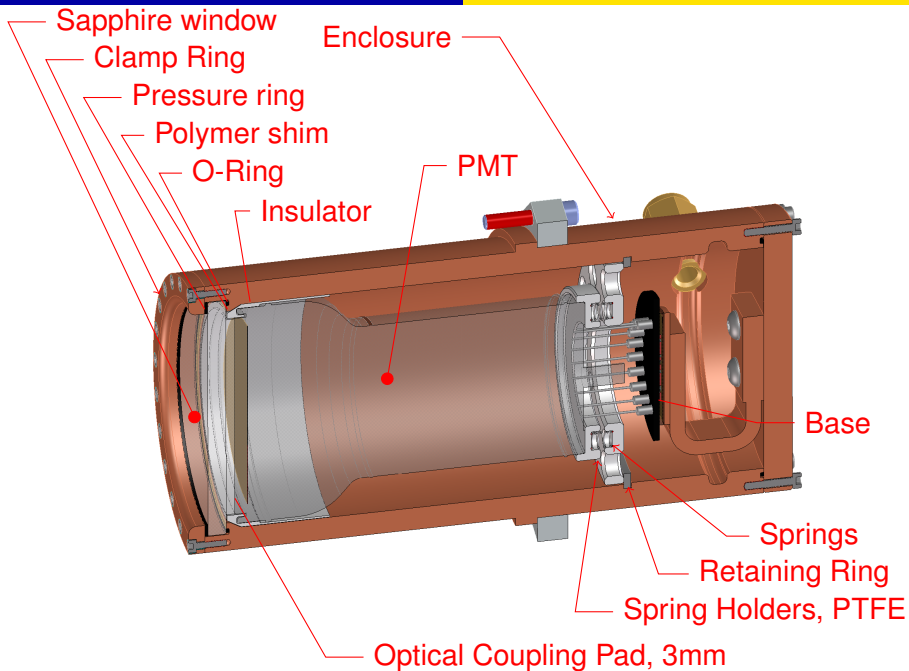


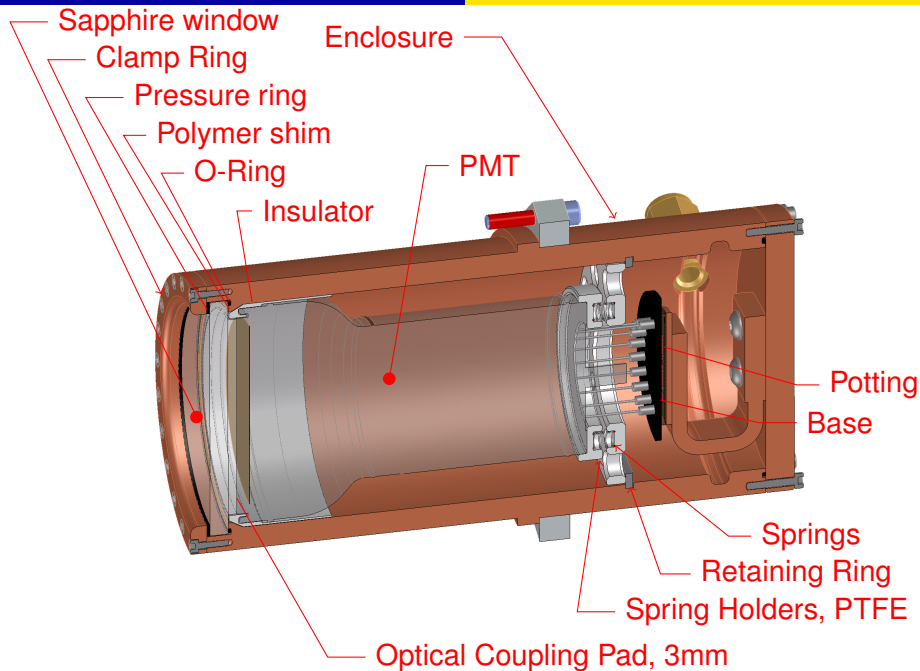


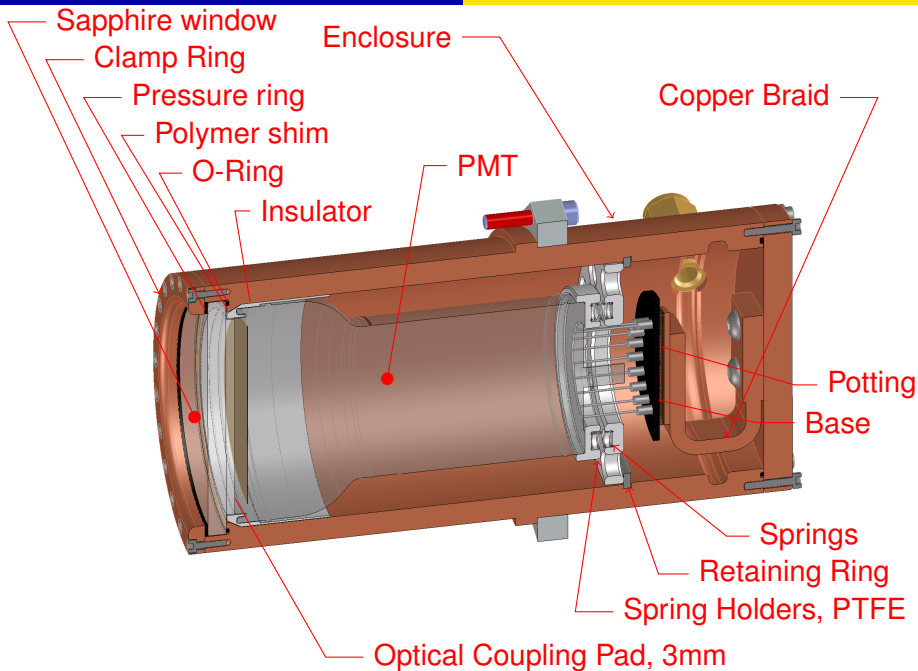


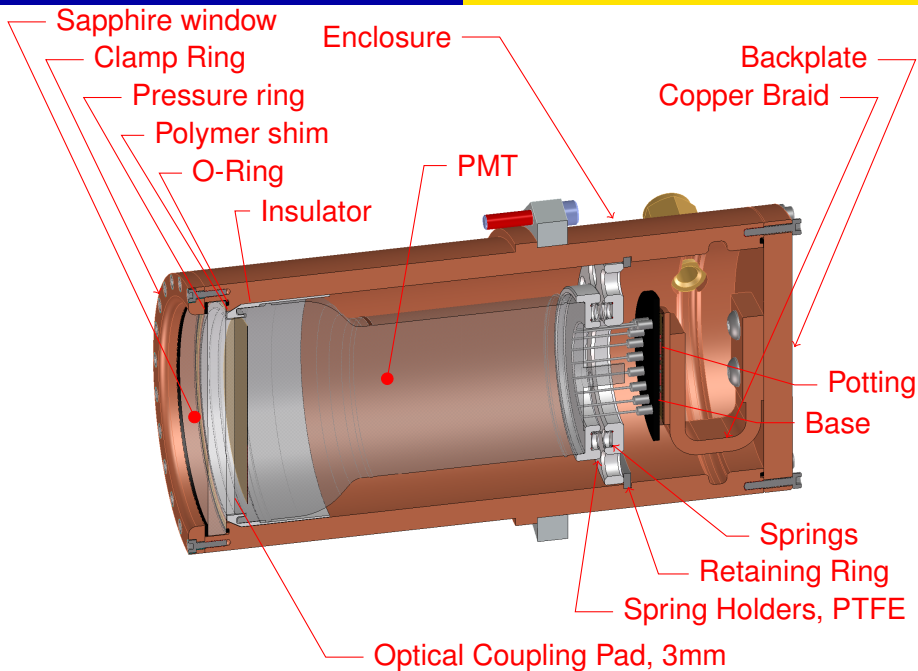


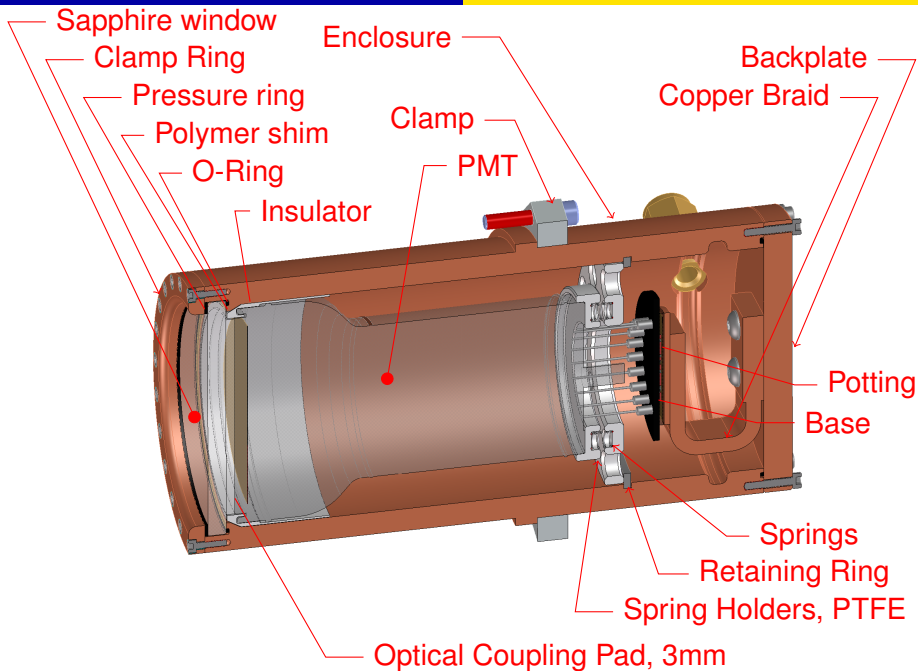


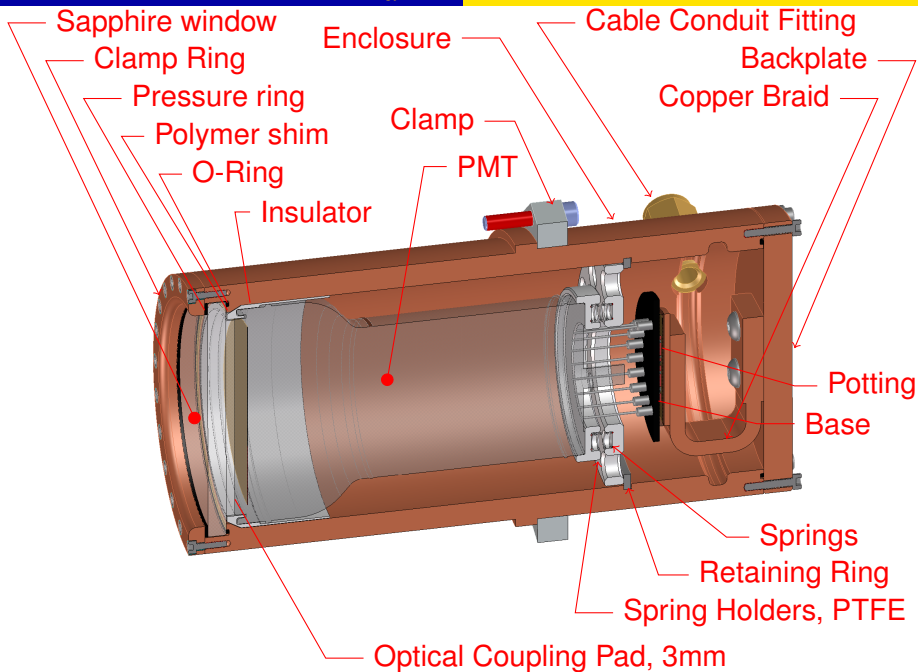


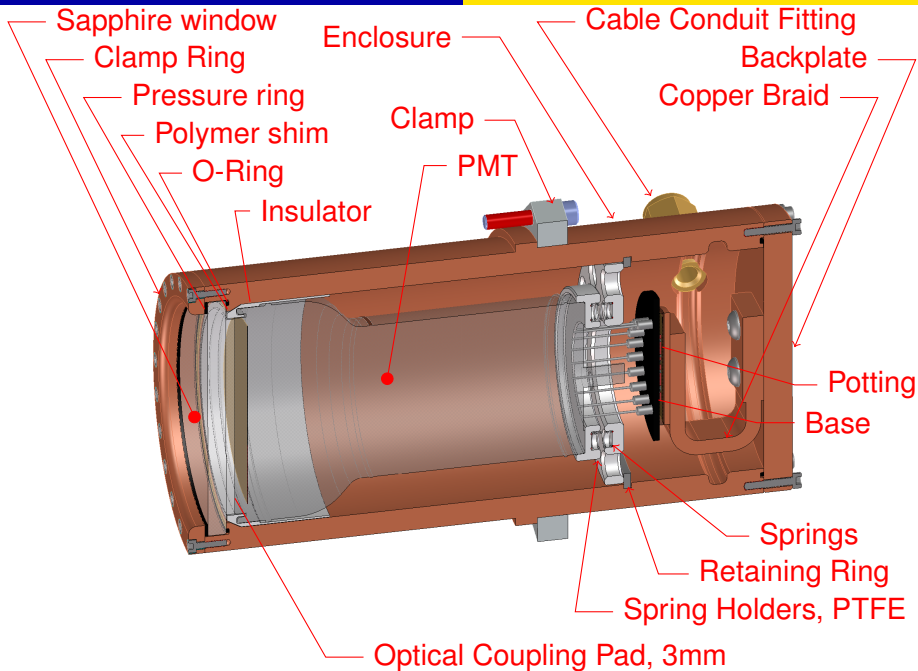


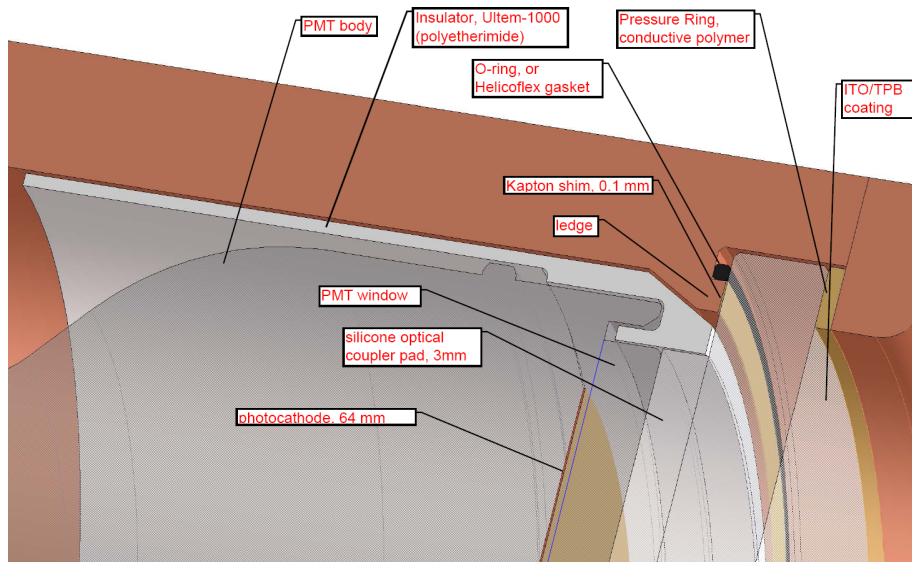


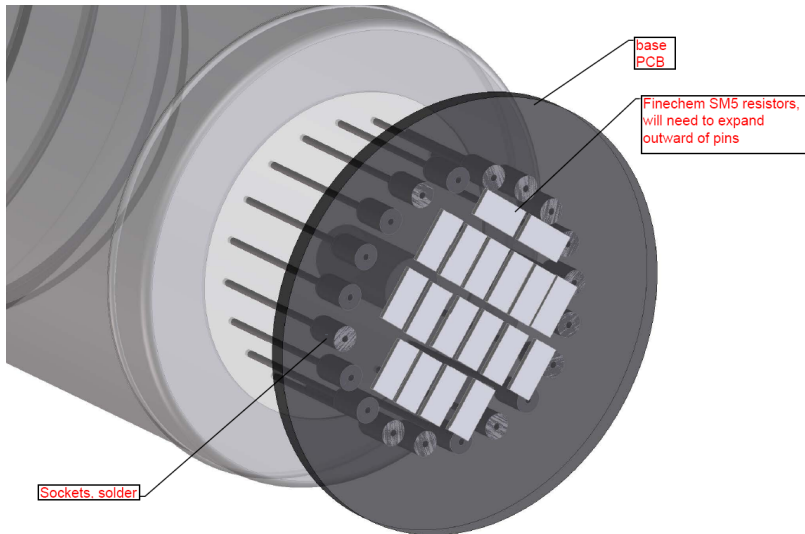


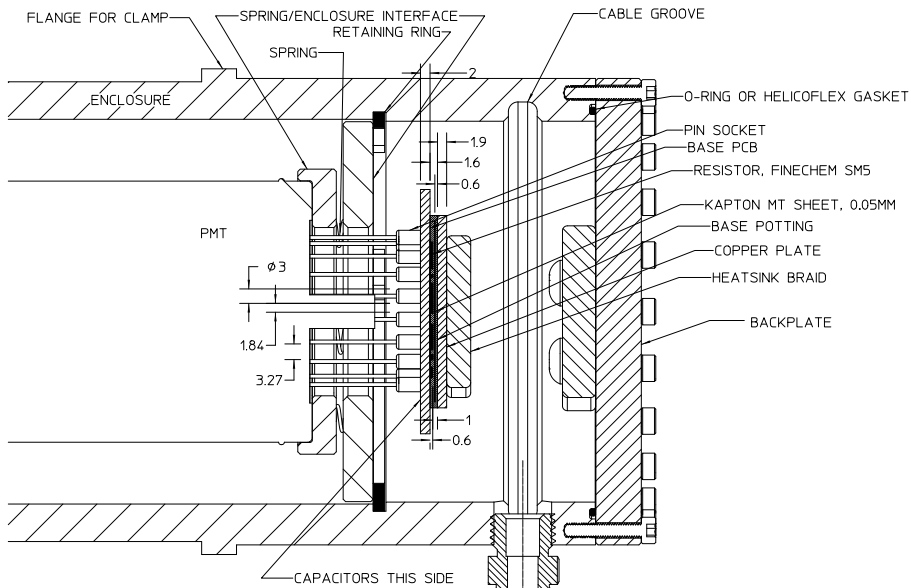


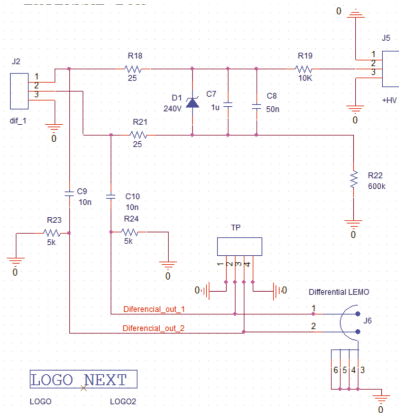
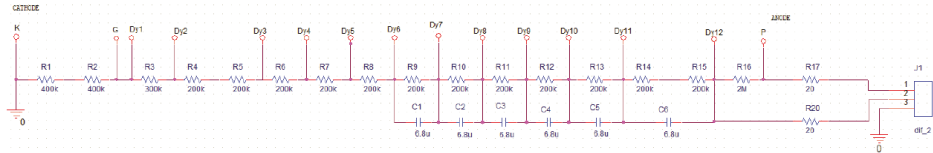












Prototyping progress

- 3 sapphire windows purchased and received, screened for gross radiopurity: Activity: <10 mBq/kg (U,late), <25 mBq/kg (Th)
- prototype enclosure parts are designed, fabricated, assembled and undergoing first vacuum tests.
- pressure vessel for testing enclosure is designed, fabricated and pressure tested, ready for use
- sample 32 pin feedthrough has been tested (preliminarily) for flashover as a function of vacuum.

For $U_z = E$, in V/cm:

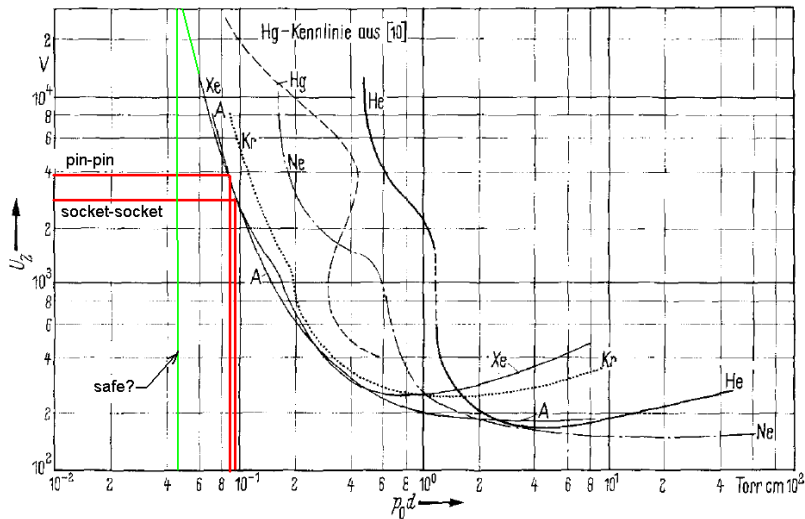
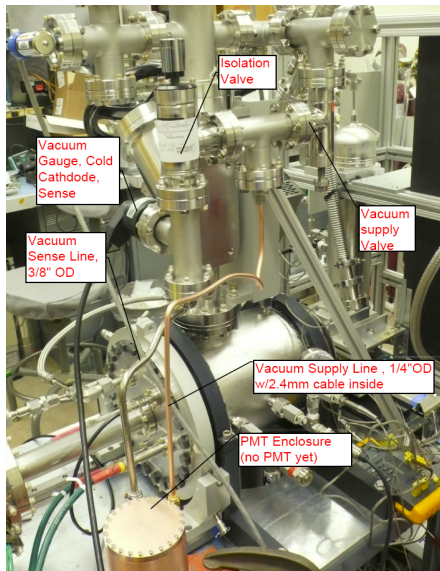
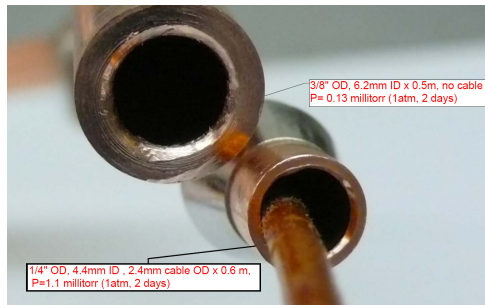
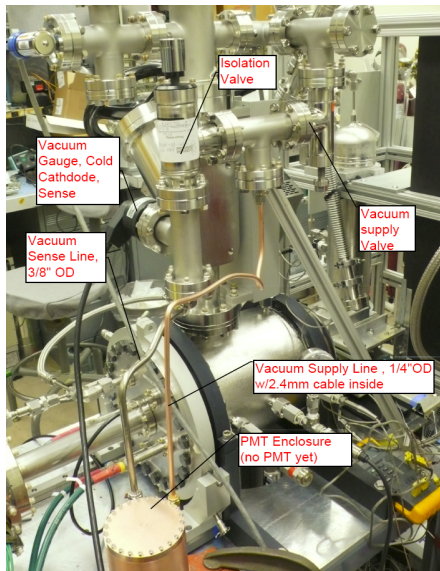
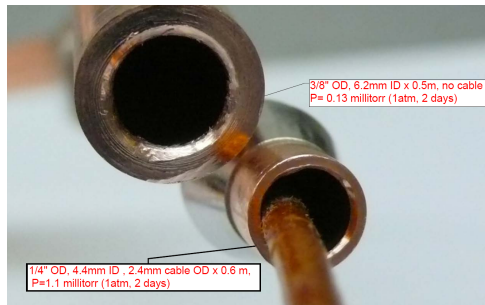
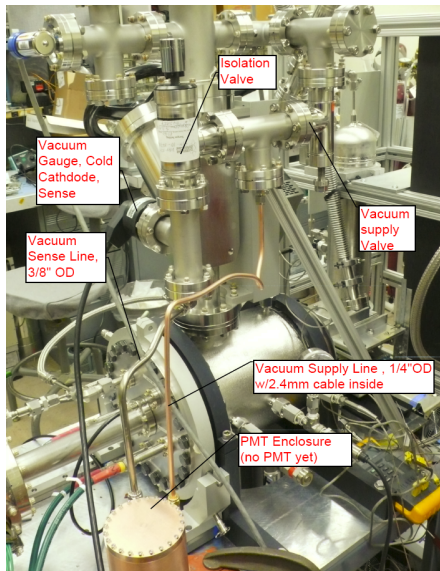


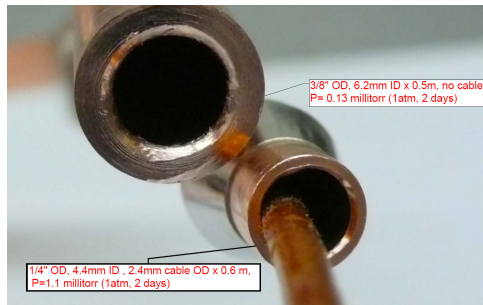
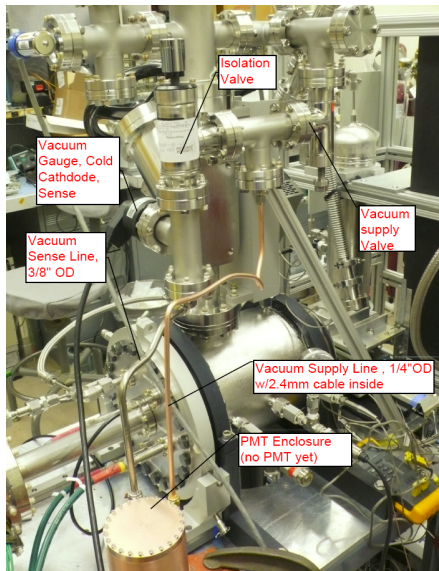
Bild 7. Zündkennlinien der Edelgase, Hg-Kennlinie aus [10].







- not yet clear ratio outgassing to permeation - RGA He leak test negative



- not yet clear ratio outgassing to permeation - RGA He leak test negative
- Nitrile O-ring seals, window, backplate
- Expect 1 decade higher at high pressure

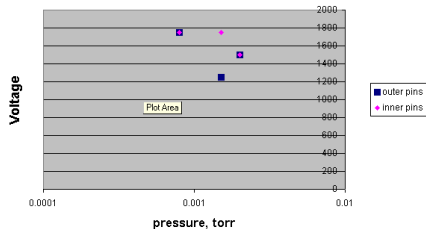
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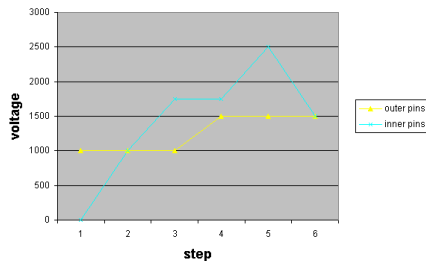
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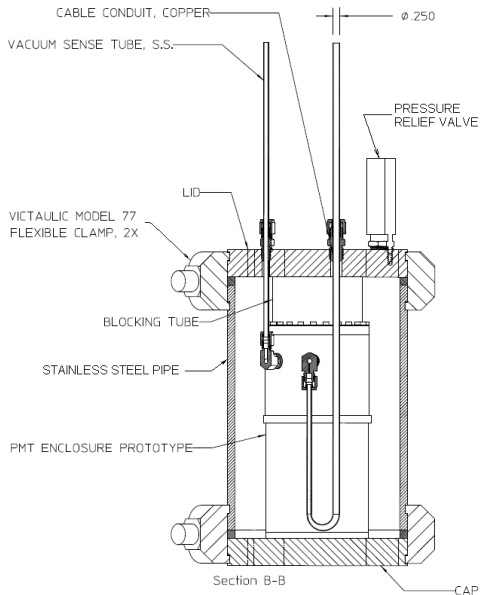
breakdown onset pressures at given voltages



Feedthrough voltages achieved so far, no sparking, $p=2 \times 10^{-5}$ torr



Pressure Testing Vessel for Permeation, HV? Studies



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- Test PMT base/pin mockup for flashover resistance and glow discharge as a function of vacuum.

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- Install enclosure module into pressure test chamber. Repeat vacuum test with 15 bar various gases (Ar, Ne, He)
- Repeat with Helicoflex gaskets - check groove dimensions
- Investigate feasibility of H₂ (5%) leak testing.
- Final test 32 pin feedthroughs for 1750 V voltage capability, as a function of vacuum, including pin connections inside vacuum.
- Test PMT base/pin mockup for flashover resistance and glow discharge as a function of vacuum.
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